

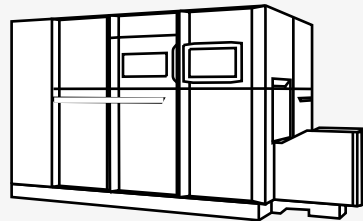


EOS P 500  
The Automation-Ready  
Manufacturing Platform for Laser Sintering  
of Plastic Parts on an Industrial Scale

# EOS P 500

## Processing Polymers at Operating Temperatures of up to 300°C

The innovative manufacturing platform produces high-quality components at the lowest cost-per-part. Thanks to clever hardware interfaces and accessories, the uptime of the EOS P 500 increases by up to 75% compared to predecessor systems and competition models.



- The innovative recoater, which applies and densifies material with a speed of up to 0,6 m/sec, as well as two powerful 70 watt lasers reduce cost-per-part by more than 30%.
- The new 3-stage filter unit and an intelligent thermo- and protective gas management ensure optimum process conditions.
- The system processes polymer materials at operating temperatures of up to 300°C enabling maximum material flexibility. Open software interfaces and user-friendly tools support application and material development.
- The EOSAME feature homogenizes the energy input, thus ensuring excellent part properties.
- SmartScaling compensates shrinkage behaviour contributing to perfect dimensional accuracy.
- Extensive sensor technology plus optical and thermal monitoring enable excellent process monitoring to meet the requirements of the aerospace and automotive industries.
- With EOSYSTEM the machine is operated intuitively. EOSPRINT 2 enables software integration in CAD systems, e.g. NX™ from Siemens and via EOSCONNECT the connection to ERP systems. Thus the EOS P 500 supports a digital control of production.
- Automated interfaces and optimized accessories reduce the cycle time drastically and ensure building process of several days duration.

### Technical Data EOS P 500

Building volume	500 x 330 x 400 mm (19.7 x 13 x 15.7 in)
Laser type	CO <sub>2</sub> ; 2 x 70 W
Building rate	up to 40 mm/h (1.6 in/h); up to 6.6 l/h
Layer thickness (depending on material)	0.06 - 0.10 - 0.12 - 0.15 - 0.18 mm (0.00236 - 0.00394 - 0.00472 - 0.00591 - 0.00709 in)
Precision optics	F-theta lens, surface module, high-speed scanner
Scan speed during build process	up to 2 x 10 m/sec (32.8 ft/s)
Power supply	400 V/100 A; max. power consumption 80 A

Dimensions (W x D x H)	3,400 x 2,100 x 2,100 mm (133.9 x 82.7 x 82.7 in)
Recommended installation space	min. 7.2 x 5.2 x 4.2 m (284 x 205 x 165 in)
Weight	approx. 7,000 kg (15,432 lb)

### Software

EOSYSTEM with EOSAME feature, EOSPRINT 2 with SmartScaling feature and EOS ParameterEditor, EOSCONNECT, EOSTATE Powderbed

### Materials

PA 2200, PEKK\*

\* currently under development

### Optional Accessories

Heating station, cooling station, IPCM P plus, unpacking and sieving station, blasting cabinet

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